

Capabilities Overview

Layers:	Rigid PCB 2 - 24 + Layers , Rigid-flex PCB 1 - 10Layers
Panel Size(max):	21" x 24"
PCB Thickness:	0.016" to 0.120"
Line & Spaces:	0.003" / 0.003" Inner Layers;0.004" Outer Layers
Hole Size:	0.008" Thru Hole (Finished Size) and Buried Via, 8:1 Aspect Ratio /0.004" HDI Microvia
Materials:	FR4,High Tg, Rogers, Halogen-free material, Teflon, Polyimide
Surface Finishes:	ENi/IAu, OSP, Immersion Silver ,Immersion Tin
Special Products:	Blind/Buried Via, HDI Microvia, Rigid Flex

More Information

Minimum Hole Position Tolerance	±0.075mm
Hole Size Tolerance	±0.075mm(PTH) ±0.05mm (NPTH)
Outline Dimension Tolerance	±0.13mm
Conductor Width Tolerance	±0.05mm or ±20% of Original Artwork
Warp & Twist Ratio	0.70%
Insulation Resistance For E/T test	10K Ω-20M Ω
Conductivity Resistance For E/T test	<50 Ω
Voltage For E/T test	300v maximum
Minimum Spacing Between hole edge and Circuit Pattern	0.2mm(PTH) 0.13mm(NPTH)
Registration Tolerance Front/Back Image	0.075mm
Layer to Layer Registration	0.075mm
Board Thickness Tolerance	±8%(t≥1.0mm) ±10%(t<1.0mm)
Plugging hole Diameter with solder mask	0.20mm-0.60mm
Minimum Solder dam Width	0.1mm
Minimum Solder Mask Clearance	0.05mm
Solder Mask Type/Silkscreen Ink	LPI(green, white, black ,red ,etc)
Impedance Control tolerance	±10%
Minimum Board thickness for V-Groove process	0.6mm
Remained Board thickness for V-Groove process	0.3mm
Thickness Tolerance for V-Groove process	±0.1mm
Minimum Spacing From V-Groove to Conductor	0.4mm
Slot Dimension Tolerance(Length/Width),Length>=2*Width	±0.125mm/±0.1mm
Au thickness	0.0762um-0.762um(Hard Au) 0.0254um-0.127um(Soft Au)
Ni thickness	2.032-7.362um